This announcement is not, and does not form any part of, an offer or invitation for the sale of securities in the United States (including its territories and dependencies, any State of the United States and the District of Columbia). Neither this announcement nor anything herein nor any copy thereof may be taken into or distributed, directly or indirectly, in or into the United States. The securities mentioned herein have not been and will not be registered under the United States Securities Act of 1933, as amended (the "Securities Act") or any other applicable securities laws of the United States, and may not be offered, sold or otherwise transferred within the United States unless the securities are registered under the Securities Act, or an exemption from the registration requirements of the Securities Act or any other applicable securities laws of the United States is available. Any public offering of securities to be made in the United States will be made by means of a prospectus that may be obtained from the Company and will contain detailed information about the Company and management, as well as financial statements. The Company does not intend to make any public offering of securities in the United States.

CIG

CIG SHANGHAI CO., LTD.
上海劍橋科技股份有限公司

(A joint stock company incorporated in the People's Republic of China with limited liability)

(Stock Code: 6166)

COMPLETION OF PLACING OF H SHARES

Joint Overall Coordinators, Joint Placing Agents and Capital Markets Intermediaries

國泰海通 GUOTAI HAITONG | 國泰君安國際 GUOTAI JUNAN INTERNATIONAL

BofA SECURITIES

The Board is pleased to announce that completion of the Placing took place on June 4, 2026 in accordance with the terms and conditions of the Placing Agreement. All conditions precedent of the Placing as set out in the Placing Agreement have been satisfied.

Reference is made to the announcement of CIG SHANGHAI CO., LTD. (the "**Company**") dated May 28, 2026 (the "**Placing Announcement**") in relation to the placement of 15,600,000 new H Shares (the "**Placing**"). Unless otherwise defined, all capitalized terms used herein shall have the same respective meanings as defined in the Placing Announcement.

COMPLETION OF THE PLACING

The Board is pleased to announce that all conditions precedent to the Placing, as set out in the Placing Agreement, have been satisfied (including the obtaining of approval for the listing of, and permission to deal in, the Placing Shares from the Listing Committee), and completion of the Placing took place on June 4, 2026 (the "**Completion**").

An aggregate of 15,600,000 new H Shares, representing approximately 16.84% of the total number of H Shares in issue as enlarged by the allotment and issue of the Placing Shares, have been successfully allotted and issued by the Company on June 4, 2026 at the Placing Price of HK$126.66 per Placing Share to not less than six Placees, who and whose ultimate beneficial owners are Independent Third Parties (to the best of the Directors' knowledge, information and belief, having made all reasonable enquiries). None of the Placees has become a substantial shareholder (as defined in the Listing Rules) of the Company immediately after the completion of the Placing.

PROCEEDS FROM THE PLACING

The aggregate gross proceeds from the Placing are approximately HK$1,975.90 million, and the aggregate net proceeds from the Placing (after deduction of the placing commission and other relevant costs and expenses of the Placing) are approximately HK$1,966.97 million.

In light of the recent booming of AI applications, the demand for high-speed optical modules has been increasing significantly, which has resulted in the shortage of core components, such as high-speed DSP chipsets for 800G and 1.6T optical modules, 100G/lane and 200G/lane silicon photonics chipsets and 70mW-200mW CW laser devices. The lead time of such core components has increased significantly, and deposits or down payments have been required to secure production capacity. In light of the above, the Company has been planning to further stockpile the core components in the coming years to ensure that the newly expanded production capacity can be fully utilized to meet customer demand. The Company considers that the proceeds from the Placing will be able to provide stable financial support for such purpose. Accordingly, 80% of the net proceeds from the Placing are expected to be applied to the strategic stockpiling of the core components; 10% of the net proceeds from the Placing are expected to be applied to supplementing the Group's working capital; and 10% of the net proceeds from the Placing are expected to be applied to other general corporate purposes.

CHANGE OF SHARE CAPITAL UPON COMPLETION OF THE PLACING

As of the date of this announcement, the total number of issued A Shares is 275,588,373. Upon completion of the Placing, (i) the total issued H Shares has increased from 77,062,000 H Shares to 92,662,000 H Shares; and (ii) the total issued A Shares remains unchanged as 275,588,373 A Shares. The total issued Shares has therefore increased from 352,650,373 Shares to 368,250,373 Shares.

The shareholding structure of the Company immediately before and after the Completion is as follows:

	Immediately before the completion of the Placing		**Immediately after the completion of the Placing**	
	Number of Shares	**Approximate percentage in the issued share capital of the Company**	**Number of Shares**	**Approximate percentage in the issued share capital of the Company**
A Shares				
Total issued A Shares	275,588,373	78.15%	275,588,373	74.84%
H Shares				
Placees	—	—	15,600,000	4.24%
Other public H Shareholders	77,062,000	21.85%	77,062,000	20.93%
Total issued H Shares	77,062,000	21.85%	92,662,000	25.16%
Total issued Shares	352,650,373	100.00%	368,250,373	100.00%

Note: The aggregate of the percentage figures in the table above may not add up to the relevant sub-total or total percentage figures shown due to rounding of the percentage figures to two decimal places.

By order of the Board
CIG SHANGHAI CO., LTD.
Mr. Gerald G Wong
Chairman of the Board, Executive Director and General Manager
(Chief Executive Officer)

Shanghai, the PRC, June 4, 2026

As at the date of this announcement, the Board of Directors of the Company comprises: (i) Mr. Gerald G Wong, Mr. Zhao Haibo, Mr. Zhao Hongwei and Mr. Zhang Jie as executive Directors; and (ii) Mr. Qin Guisen, Mr. Yao Minglong and Ms. Yuen Shuk Yee as independent non-executive Directors.